

In the Claims:

1. (Currently Amended) A method of forming a microlens comprising the steps of:
providing a wafer having a first planarization layer formed on the wafer, color filters formed over the first planarization layer, and a second planarization layer formed on the color filters in a first region, the wafer having an indentation formed therein in a second region;
forming a layer of a filler material over the second planarization layer in the first region and over the wafer in the second region, thereby substantially filling the indentation with [[a]] the filler material;
removing a portion of the filler material such that the filler material in the indentation remains;
forming a microlens material over the second planarization layer;
removing a portion of the microlens material;
substantially removing the filler material; and
forming the microlens from the remaining microlens material.
2. (Original) The method of claim 1, wherein the indentation is a bond pad area or a scribe line.
3. (Original) The method of claim 1, wherein the filler material is a photoresist material.
4. (Original) The method of claim 1, wherein the filler material is a positive photoresist material.

5. (Original) The method of claim 1, wherein the microlens material is a photoresist material.
6. (Original) The method of claim 1, wherein the microlens material is a positive photoresist material.
7. (Original) The method of claim 1, wherein the step of removing a portion of the microlens material includes the steps of:
 - applying a mask on the microlens material to define the microlens;
 - exposing the microlens material with the mask; and
 - developing the microlens material, wherein the microlens material defined to be the microlens remains.
8. (Original) The method of claim 1, wherein the filler material is a photoresist material and the step of substantially removing the filler material includes the steps of:
 - exposing the filler material; and
 - developing the filler material to substantially remove the filler material.
9. (Currently Amended) A method of forming a microlens comprising the steps of:
 - providing a wafer having a first planarization layer formed on the wafer, color filters formed over the first planarization layer, and a second planarization layer formed over the color filters in a first region, the wafer having an indentation formed therein in a second region;
 - substantially filling the indentation with a photoresist filler material, the filling being performed at least in part by applying a layer of photoresist material over the second

planarization layer in the first region and in the indentation in the second region and by removing photoresist material not located in the indentation;

forming a microlens material over the second planarization layer;

exposing the microlens material and the photoresist filler material;

developing the microlens material and the photoresist filler material; and

forming the microlens from the remaining microlens material.

10. (Original) The method of claim 9, wherein the indentation is a bond pad area and scribe line.

11. (Original) The method of claim 9, wherein the photoresist filler material is a positive photoresist material.

12. Cancelled.

13. (Original) The method of claim 9, wherein the microlens material is a photoresist material.

14. (Original) The method of claim 9, wherein the microlens material is a positive photoresist material.

15. (Original) The method of claim 9, wherein the step of exposing the microlens material and the photoresist filler material comprises exposing the microlens material to a first energy and exposing the photoresist filler material to a second energy, wherein the first energy is not equivalent to the second energy.

16. (Original) The method of claim 9, wherein the step of exposing the microlens material and the photoresist filler material comprises exposing the microlens material to a first energy and exposing the photoresist filler material to a second energy, wherein the first energy is about 60 mj to 600 mj and the second energy is about 600 mj to 2000 mj.

17. (Original) The method of claim 9, wherein the step of removing the microlens material includes the steps of:

applying a mask on the microlens material to define the microlens;

exposing the microlens material with the mask; and

developing the microlens material, wherein the microlens material defined to be the microlens remains.

18. (Original) The method of claim 9, wherein the step of developing the microlens material and the photoresist filler material is performed in a single developing stage.

19. (Currently Amended) A method of forming a microlens comprising the steps of:

providing a wafer having a first planarization layer formed on the wafer, color filters formed over the first planarization layer, and a second planarization layer formed on the color filters in a first region, the wafer having an indentation formed therein in a second region;

forming a filler layer over the second planarization layer in the first region and in the indentation in the second region, thereby substantially filling the indentation with a filler-
material;

substantially removing the filler layer not located in the indentation;

forming a microlens material over the second planarization layer;

removing excess microlens material;
forming a mask on the wafer, the mask defining the indentation;
etching the wafer in a pattern aligned with the mask to remove the ~~photoresist filler~~
~~material layer~~; and
forming the microlens.

20. (Original) The method of claim 19, wherein the indentation is a bond pad area or a scribe line.

21. (Currently Amended) The method of claim 19, wherein the filler ~~material is layer~~
comprises a photoresist material.

22. (Currently Amended) The method of claim 19, wherein the filler ~~material is layer~~
comprises a positive photoresist material.

23. Cancelled.

24. (Original) The method of claim 19, wherein the microlens material is a photoresist material.

25. (Original) The method of claim 19, wherein the microlens material is a positive photoresist material.

26. (Original) The method of claim 19, wherein the step of removing excess microlens material includes the steps of:

applying a second mask on the microlens material defining the microlens;
exposing uncovered areas of the microlens material with the second mask; and
developing the microlens material to remove the microlens material not defined as the
microlens.

27. (Original) The method of claim 19, wherein the mask is formed from a photoresist.

28. (Original) The method of claim 19, wherein the step of etching includes the step of
removing the mask.